EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1186	(compensat$4 adjust $4) same ("IC" chip semiconductor) same (position location) same packag$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 13:53
S2	1428	(compensat$4 adjust $4 rotation) same ("IC" chip semiconductor) same (position location) same packag$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 13:53
S3	282	S2 same (wiring bonding)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 13:54
S4	3	S3 and (wiring bonding) same (design adj2 rule)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 13:54
S5	9	("4864514" | "5465217" | "5498767" | "5608638" | "6032356" | "6072700" | "6256549" | "6357036" | "6714828").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/07/23 13:57
S6	7347	(716/1,12-15,18.ccls. 703/13,14.ccls.)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:03
S7	308	(compensat$4 adjust $4 rotation) same ("IC" chip semiconductor) same (position location) same packag$4 same (via via$hole through $hole through adj hole interposer pin bad)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:04

S8	3	S6 and S7	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:04
S10	1150	(compensat$4 adjust $4 rotation arrang$4) same ("IC" chip semiconductor) same (position location) same packag$4 same (via via$hole through $hole through adj hole interposer pin bad)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:06
S11	9	S6 and S10	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:06
S12	4184	(compensat$4 adjust $4) same ("IC" chip semiconductor) same (position location) same mount$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:22
S13	3	S12 and (wiring bonding) same (design adj2 rule)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:22
S14	1594	S12 and (wiring bonding)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:23
S16	9133	(compensat$4 adjust $4 rotation arrang$4) same ("IC" chip semiconductor) same (position location) same (via via$hole through$hole through adj hole interposer pin bad)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:24
S17	392	S14 and S16	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:25

S18	2	S17 and (design adj2 rule)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:25
S19	5901	(align$5 rotation) same ("IC" chip semiconductor) same (position location) same (via via$hole through$hole through adj hole interposer pin bad)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:26
S20	24	S6 and S19	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:26
S21	403	(align$5 rotation) same ("IC" chip semiconductor) same (position location) same (via via$hole through$hole through adj hole interposer pin bad) same mount $4 same (PCB board)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:30
S22	17	S14 and S21	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:30
S23	1602	(align$5 rotation compensat$4) same ("IC" chip semiconductor) with (position location) with (via via$hole through$hole through adj hole interposer pin bad)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:45
S24	1086	(align$5 rotation compensat$4) with ("IC" chip semiconductor) with (position location) with (via via$hole through$hole through adj hole interposer pin bad)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:45

S25	585	S24 and (wiring bonding)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:46
S26	27634	L25and (design adj2 rule)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:46
S27	49	S25 and (design adj2 rule)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:46
S28	980	(align$5 rotation compensat$4) with ("IC" chip semiconductor) with (position location) same (PCB board)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:47
S29	525	S28 and (wiring bonding)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:47
S30	3	S29 and (wiring bonding) same (design adj2 rule)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:48
S31	8	S29 and (design adj2 rule)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:49
S32	9	S28 and (design adj2 rule)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/23 14:50

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